





30V N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

V _{(BR)DSS}	R _{DS(on)}	I _D T _A = 25°C
30V	20mΩ @ V _{GS} = 10V	16.7A
	34mΩ @ V _{GS} = 4.5V	12.6A

Description and Applications

This new generation MOSFET has been designed to minimize the onstate resistance ($R_{DS(on)}$) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

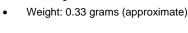
- Backlighting
- DC-DC Converters
- Power management functions

Features and Benefits

- · Low on-resistance
- · Fast switching speed
- · "Green" Component and RoHS compliant

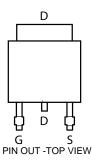
Mechanical Data

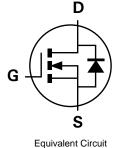
- Case: TO252-3L
- Case Material: Molded Plastic "Green" Molding Compound, UL Flammability Classification Rating 94V-0 (Note 1)
- Moisture Sensitivity: Level 1 per J-STD-020D
- Terminal Connections: See Diagram
- Terminals: Matte Tin Finish annealed over Copper leadframe. Solderable per MIL-STD-202, Method 208 🚳
- Marking Information: See Below
 Ordering Information: See Below





TOP VIEW





Ordering Information (Note 1)

Product	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
DMN3020LK3-13	N3020L	13	16	2,500

1. Diodes, Inc. defines "Green" products as those which are Eu RoHS compliant and contain no halogens or antimony compounds; further information about Diodes Inc.'s "Green" Policy can be found on our website. For packaging details, go to our website.

Marking Information

Notes:



Oll = Manufacturer's Marking
N3020L = Product Type Marking Code
YYWW = Date Code Marking
YY = Last two digits of year (ex: 09 = 2009)
WW = Week (01-52)





Maximum Ratings @T_A = 25°C unless otherwise specified

Cha	racteristic		Symbol	Value	Unit
Drain-Source voltage			V_{DSS}	30	V
Gate-Source voltage			V_{GS}	V _{GS} ±20	
		(Note 3)	-	16.7	
Continuous Drain current	$V_{GS} = 10V$	T _A =70°C (Note 3)		13.3	Α
		(Note 2)		11.3	
Pulsed Drain current V _{GS} = 10V		(Note 4)	I _{DM}	51	Α
Continuous Source current (Body diode) ((Note 3)	I _S	12	Α
Pulsed Source current (Body diode) (Note			I _{SM}	51	A

Thermal Characteristics @TA = 25°C unless otherwise specified

Characteristic		Symbol	Value	Unit	
	(Note 2)		4.1 32.5		
Power dissipation Linear derating factor	(Note 3)	P _D	8.9 71.4	W mW/°C	
	(Note 5)		2.17 17.4		
Thermal Resistance, Junction to Ambient	(Note 2) (Note 3)	$R_{ hetaJA}$	30.8 14.0	°C/W	
Thermal Resistance, Junction to Lead	(Note 5) (Note 6)	$R_{ hetaJL}$	57.6 2.24	°C/W	
Operating and storage temperature range	`	T_J , T_{STG}	-55 to 150	°C	

Notes:

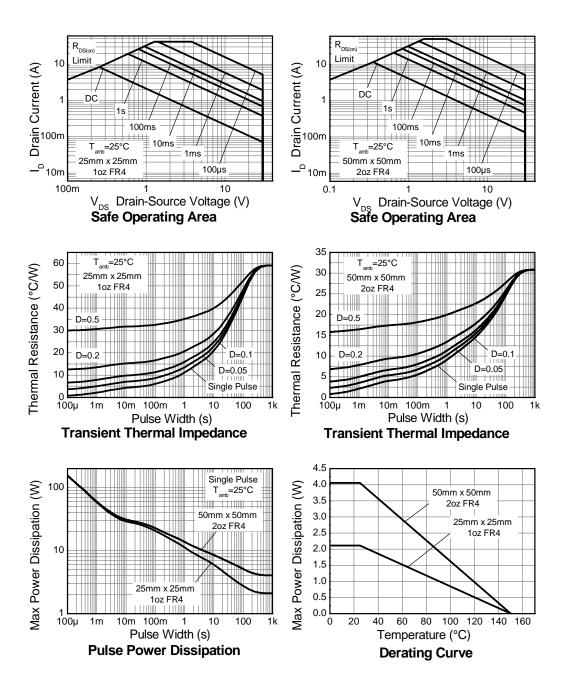
- 2. For a device surface mounted on 50mm x 50mm x 1.6mm FR4 PCB with high coverage of single sided 2oz copper, in still air conditions; the device is measured when operating in a steady-state condition.
- 3. Same as note 2, except the device is measured at $t \le 10$ sec.
- 4. Same as note 2, except the device is pulsed with D = 0.02 and pulse width 300 µs. The pulse current is limited by the maximum junction temperature.
- 5. For a device surface mounted on 25mm x 25mm x 1.6mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions; the device is
- measured when operating in a steady-state condition.

 6. Thermal resistance from junction to solder-point (at the end of the drain lead).





Thermal Characteristics







Electrical Characteristics @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition		
OFF CHARACTERISTICS								
Drain-Source Breakdown Voltage	BV _{DSS}	30	_	_	V	$I_D = 250 \mu A, V_{GS} = 0 V$		
Zero Gate Voltage Drain Current	I _{DSS}	_	_	0.5	μА	V _{DS} = 30V, V _{GS} = 0V		
Gate-Source Leakage	I _{GSS}	_	_	±100	nA	V _{GS} = ±20V, V _{DS} = 0V		
ON CHARACTERISTICS	ON CHARACTERISTICS							
Gate Threshold Voltage	$V_{GS(th)}$	1.0	_	3.0	V	$I_D=250\mu A,\ V_{DS}=V_{GS}$		
Static Drain-Source On-Resistance (Note 7)	P== (01)			0.020	Ω	V _{GS} = 10V, I _D = 7.0A		
Glatic Dialif-Source Off-Nesistance (Note 1)	R _{DS (ON)}		_	0.034	32	V _{GS} = 4.5V, I _D = 6.0A		
Forward Transconductance (Notes 7 & 8)	g fs		16.5	_	S	V _{DS} = 15V, I _D = 7.1A		
Diode Forward Voltage (Note 7)	V _{SD}	_	0.82	1.2	V	I _S = 1.7A, V _{GS} = 0V		
Reverse recovery time (Note 8)	t _{rr}		12	_	ns	1 2 2 4 4:/44 4 2 2 4 / 2		
Reverse recovery charge (Note 8)	Q _{rr}	_	4.8	_	nC	I _S = 2.2A, di/dt= 100A/μs		
DYNAMIC CHARACTERISTICS (Note 8)			•	•	•			
Input Capacitance	C _{iss}	_	608	_	pF			
Output Capacitance	Coss	_	132	_	pF	V _{DS} = 15V, V _{GS} = 0V -f= 1MHz		
Reverse Transfer Capacitance	C _{rss}	_	71	_	pF	1= 11011 12		
Total Gate Charge	Qg	_	6.3	_	nC	V _{DS} = 15V, V _{GS} = 4.5V I _D = 7A		
Total Gate Charge	Qg	_	12.9	_	nC			
Gate-Source Charge	Q _{gs}	_	2.5	_	nC	$V_{DS} = 15V, V_{GS} = 10V$		
Gate-Drain Charge	Q_{gd}	_	2.5	_	nC	-I _D = 7A		
Turn-On Delay Time (Note 9)	t _{D(on)}	_	2.9	_	ns			
Turn-On Rise Time (Note 9)	t _r	_	3.3	_	ns	V _{DD} = 15V, V _{GS} = 10V		
Turn-Off Delay Time (Note 9)	t _{D(off)}	_	16	_	ns	I _D = 1A, R _G ≅ 6.0Ω		
Turn-Off Fall Time (Note 9)	t _f		8		ns	<u> </u>		

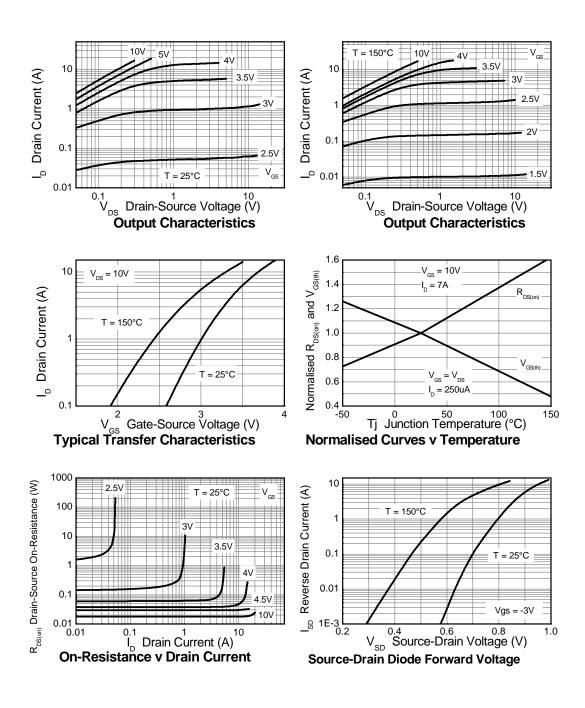
Notes:

- 7. Measured under pulsed conditions. Pulse width $\leq 300 \mu s;$ duty cycle $\leq 2\%$
- For design aid only, not subject to production testing.
 Switching characteristics are independent of operating junction temperatures.



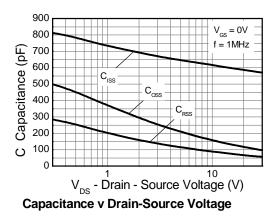


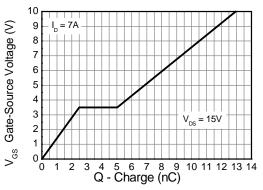
Typical Characteristics





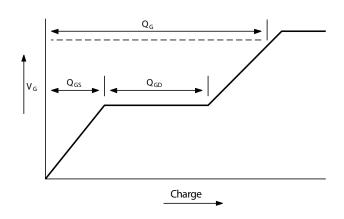
Typical Characteristics - continued





Gate-Source Voltage v Gate Charge

Test Circuits

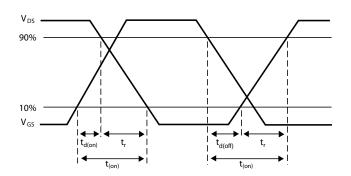


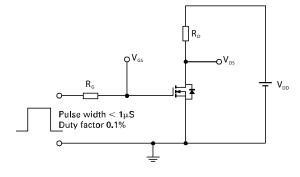
DU.T V_{os}

Current regulator

Basic gate charge waveform

Gate charge test circuit



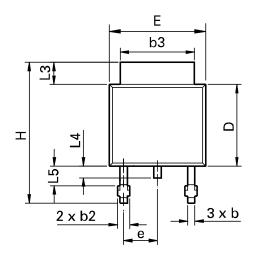


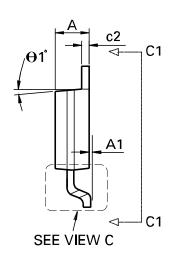
Switching time waveforms

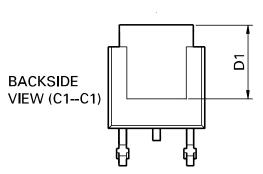
Switching time test circuit

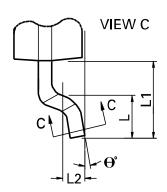


Package Outline Dimensions





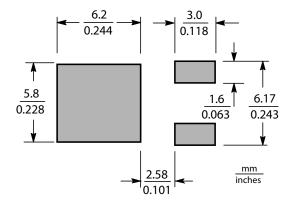




DIM	/ Inches		Millimeters		DIM	Inches		Millimeters	
	Min	Max	Min	Max		Min	Max	Min	Max
Α	0.086	0.094	2.18	2.39	е	0.090 BSC		2.29 BSC	
A 1	-	0.005	-	0.127	Н	0.370	0.410	9.40	10.41
b	0.020	0.035	0.508	0.89	L	0.055	0.070	1.40	1.78
b2	0.030	0.045	0.762	1.14	L1	0.108 REF		2.74 REF	
b3	0.205	0.215	5.21	5.46	L2	0.020 BSC		0.508 BSC	
С	0.018	0.024	0.457	0.61	L3	0.035	0.065	0.89	1.65
c2	0.018	0.023	0.457	0.584	L4	0.025	0.040	0.635	1.016
D	0.213	0.245	5.41	6.22	L5	0.045	0.060	1.14	1.52
D1	0.205	-	5.21	-	θ1°	0°	10°	0°	10°
E	0.250	0.265	6.35	6.73	θ°	0°	15°	0°	15°
E1	0.170	-	4.32	-	-	-	-	-	-



Suggested Pad Layout



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